

Application No.: 10/649,519

Docket No.: 200300040-1

AMENDMENTS TO THE SPECIFICATION

[0001] This application is related to concurrently filed, co-pending, and commonly assigned U.S. Patent Application Serial No. 10/649,518, filed August 25, 2003 [~~Attorney docket 200300041-1~~], titled "METHOD OF ASSEMBLY OF A WEDGE THERMAL INTERFACE TO ALLOW EXPANSION AFTER ASSEMBLY"; co-pending and commonly assigned U.S. Patent Application Serial No. 10/419,386, titled "HEAT SINK HOLD-DOWN WITH FAN-MODULE ATTACH LOCATION," filed April 21, 2003; co-pending and commonly assigned U.S. Patent Application Serial No. 10/419,373, titled "VARIABLE-GAP THERMAL-INTERFACE DEVICE," filed April 21, 2003; co-pending and commonly assigned U.S. Patent Application Serial No. 10/419,406, titled "VARIABLE-WEDGE THERMAL-INTERFACE DEVICE," filed April 21, 2003; and co-pending and commonly assigned U.S. Patent Application Serial No. 10/074,642, titled THERMAL TRANSFER INTERFACE SYSTEM AND METHODS," filed Feb. 12, 2002; the disclosures of all of which are hereby incorporated herein by reference.